

SRM Institute of Science and Technology Tiruchirappalli Faculty of Engineering and Technology Dept. of Electronics and Communication Engineering

21ECC303T VLSI Design and Technology

Unit II – MOS Transistor

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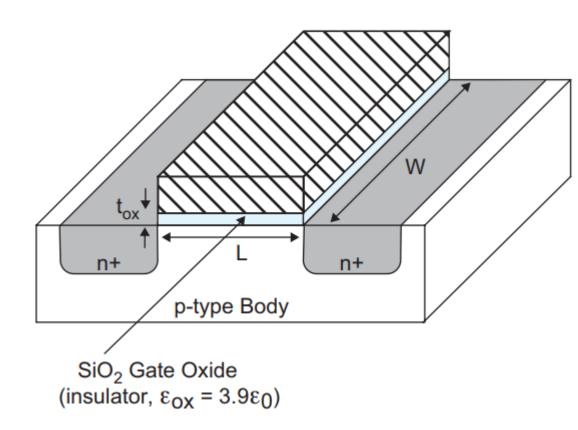
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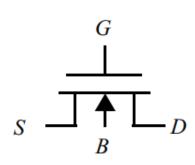
MOS Transistor Overview

- The MOSFET is a four terminal device.
- The voltage applied to the *gate* terminal determines if and how much current flows between the *source* and the *drain* ports.
- The *body* represents the fourth terminal of the transistor.
- Its function is secondary as it only serves to modulate the device characteristics and parameters
- The MOS transistor is a *majority-carrier* device in which the current in a conducting channel between the source and drain is controlled by a voltage applied to the gate.
- In an nMOS transistor, the majority carriers are electrons; in a pMOS transistor, the majority carriers are holes.

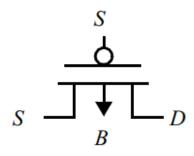


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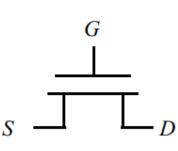
MOS Transistor Circuit Symbols



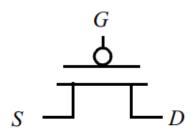
(a) NMOS transistor as 4-terminal device



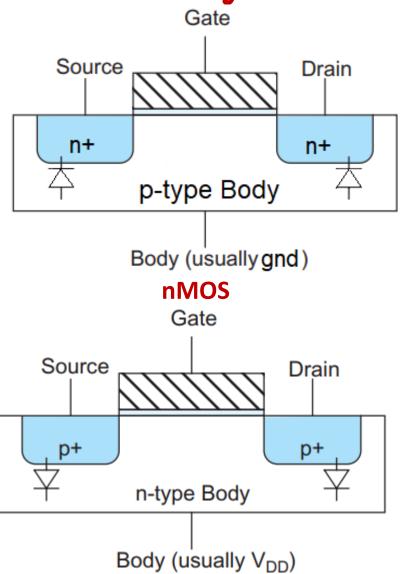
(a) PMOS transistor as 4-terminal device



(b) NMOS transistor as 3-terminal device

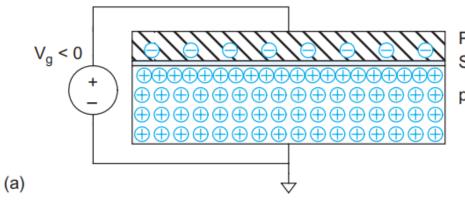


(d) PMOS transistor as 3-terminal device





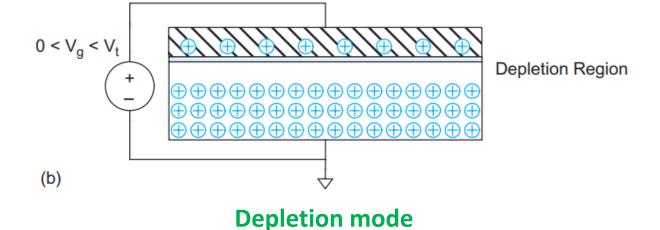
nMOS Transistor Modes of operation

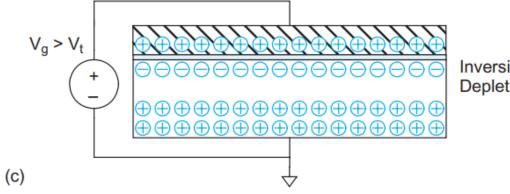


Polysilicon Gate Silicon Dioxide Insulator

p-type Body







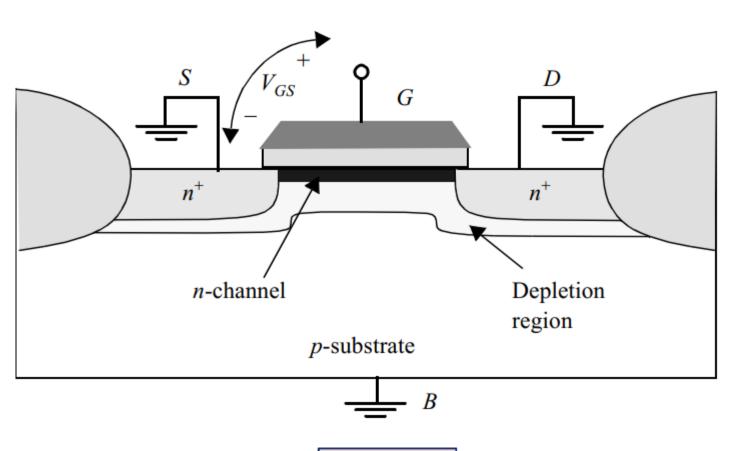
Inversion Region Depletion Region

Inversion mode



nMOS Cutoff region

$$V_{GS} < V_T \text{ or } V_{GS} > V_T, V_{DS} = 0$$

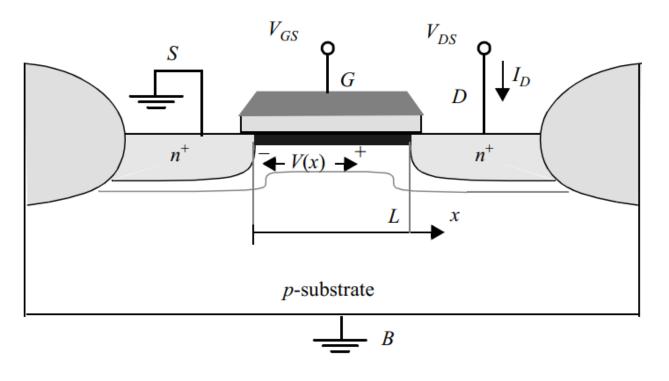


$$I_D = 0$$



nMOS Linear region

$$V_{GS} > V_{T}$$
 and $0 < V_{DS} < V_{DS,sat}$; $V_{DS,sat} = V_{GS} - V_{T}$



$$I_{ds} = \beta \left(V_{gs} - V_t - \frac{1}{2} V_{ds} \right) V_{ds} - - - (8) ; V_{GS} \ge V_{th} \text{ and } V_{DS} < V_{Sat} = V_{GS} - V_{th}$$



nMOS Saturation region

$$V_{GS}>V_{T}$$
 and $0=V_{DS,sat}$; $V_{DS,sat}=V_{GS}-V_{T}$

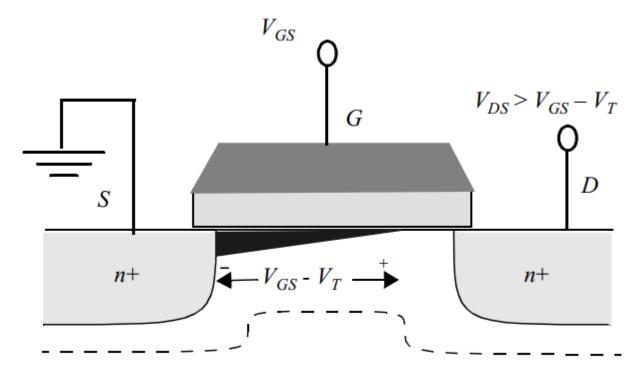


Figure 3.16 NMOS transistor under pinch-off conditions.

$$I_{ds} = \beta \left[\frac{V_{ds}^2}{2}\right] --- (9)$$



Drain current in three regions

$$\beta = \mu C_{\text{ox}} \frac{W}{L}; \ V_{GT} = V_{gs} - V_{t}$$

$$I_{ds} = \begin{cases} 0 & V_{gs} < V_t & \text{Cutoff} \\ \beta \left(V_{GT} - V_{ds} / 2\right) V_{ds} & V_{ds} < V_{\text{dsat}} & \text{Linear} \\ \frac{\beta}{2} V_{GT}^2 & V_{ds} > V_{\text{dsat}} & \text{Saturation} \end{cases}$$



MOS Transistors - Problem

Consider an nMOS transistor in a 65 nm process with a minimum drawn channel length of 50 nm (λ = 25 nm). Let $W/L = 4/2 \lambda$ (i.e., 0.1/0.05 μ m). In this process, the gate oxide thickness is 10.5 Å. Estimate the high-field mobility of electrons to be 80 cm²/V·s at 70 °C. The threshold voltage is 0.3 V. Plot I_{ds} vs. V_{ds} for V_{gs} = 0, 0.2, 0.4, 0.6, 0.8, and 1.0 V using the long-channel model.

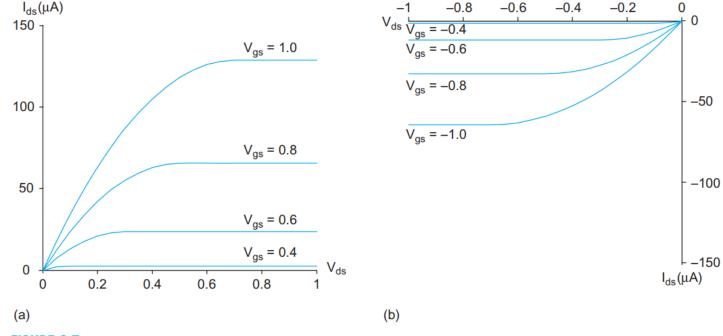
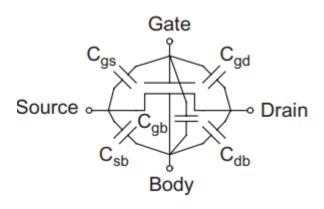


FIGURE 2.7 I-V characteristics of ideal 4/2 λ (a) nMOS and (b) pMOS transistors



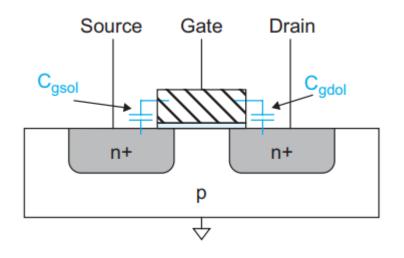
MOS Transistors - Capacitances



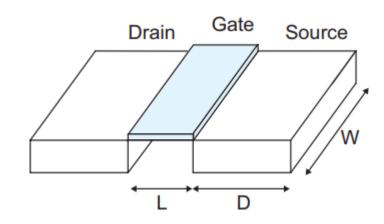
Parameter	Cutoff	Linear	Saturation
C_{gb}	$\leq C_0$	0	0
C_{gs}	0	$C_0/2$	2/3 C ₀
C_{gd}	0	$C_0/2$	0
$C_g = C_{gs} + C_{gd} + C_{gb}$	C_0	C_0	2/3 C ₀



MOS Transistors - Overlap and Diffusion Capacitances



$$\begin{split} &C_{gsol(\text{overlap})} = C_{gsol}W\\ &C_{gdol(\text{overlap})} = C_{gdol}W \end{split}$$



$$C_{sb} = AS \times C_{jbs} + PS \times C_{jbssw}$$

$$C_{jbs} = C_J \left(1 + \frac{V_{sb}}{\psi_0} \right)^{-M_J} \qquad C_{jbssw} = C_{JSW} \left(1 + \frac{V_{sb}}{\psi_{SW}} \right)^{-M_{JSW}}$$

$$\psi_0 = v_T \ln \frac{N_A N_D}{n_i^2}$$